



24AA32A/24LC32A

32K I²C™ Serial EEPROM

Device Selection Table

Part Number	V _{CC} Range	Max. Clock Frequency	Temp. Ranges
24AA32A	1.7-5.5	400 kHz ⁽¹⁾	I
24LC32A	2.5-5.5	400 kHz	I, E

Note 1: 100 kHz for V_{CC} < 2.5V

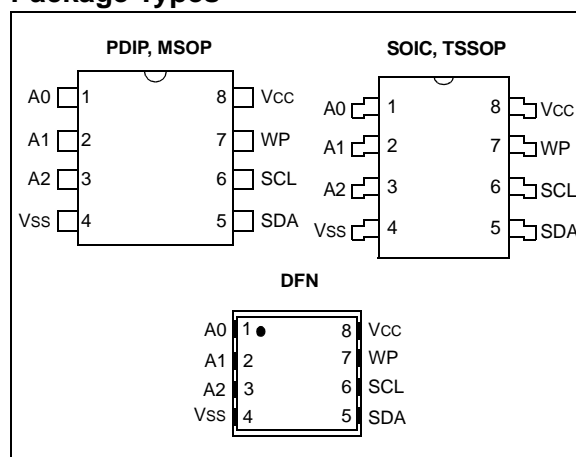
Features:

- Single supply with operation down to 1.7V for 24AA32A devices, 2.5V for 24LC32A devices
- Low-power CMOS technology:
 - Active current 1 mA, typical
 - Standby current 1 μ A, typical
- 2-wire serial interface, I²C™ compatible
- Cascadable up to eight devices
- Schmitt Trigger inputs for noise suppression
- Output slope control to eliminate ground bounce
- 100 kHz and 400 kHz clock compatibility
- Page write time 5 ms max.
- Self-timed erase/write cycle
- 32-byte page write buffer
- Hardware write-protect
- ESD protection > 4,000V
- More than 1 million erase/write cycles
- Data retention > 200 years
- Factory programming available
- Packages include 8-lead PDIP, SOIC, TSSOP, MSOP and DFN
- Pb-free and RoHS compliant
- Temperature ranges:
 - Industrial (I): -40°C to +85°C
 - Automotive (E): -40°C to +125°C

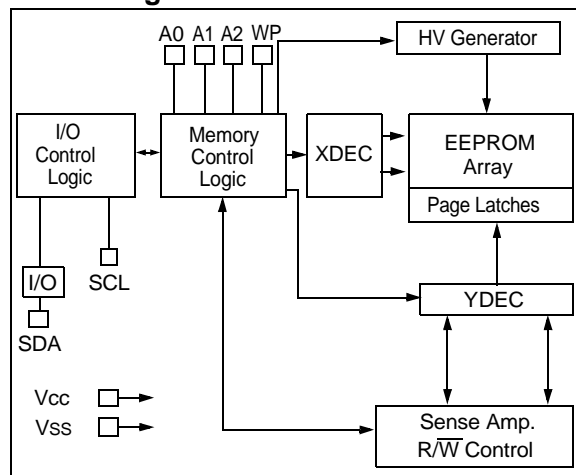
Description:

The Microchip Technology Inc. 24AA32A/24LC32A (24XX32A*) is a 32 Kbit Electrically Erasable PROM. The device is organized as a single block of 4K x 8-bit memory with a 2-wire serial interface. Low-voltage design permits operation down to 1.7V, with standby and active currents of only 1 μ A and 1 mA, respectively. It has been developed for advanced, low-power applications such as personal communications or data acquisition. The 24XX32A also has a page write capability for up to 32 bytes of data. Functional address lines allow up to eight devices on the same bus, for up to 256 Kbits address space. The 24XX32A is available in the standard 8-pin PDIP, surface mount SOIC, TSSOP, 2x3 DFN and MSOP packages.

Package Types



Block Diagram



*24XX32A is used in this document as a generic part number for the 24AA32A/24LC32A devices.

24AA32A/24LC32A

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings (†)

V _{CC}	6.5V
All inputs and outputs w.r.t. V _{SS}	-0.3V to V _{CC} +1.0V
Storage temperature	-65°C to +150°C
Ambient temperature with power applied.....	-40°C to +125°C
ESD protection on all pins	≥ 4 kV

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 1-1: DC CHARACTERISTICS

DC CHARACTERISTICS			Industrial (I): TA = -40°C to +85°C, V _{CC} = +1.7V to +5.5V Automotive (E): TA = -40°C to +125°C, V _{CC} = +2.5V to +5.5V				
Param. No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
D1	—	A0, A1, A2, WP, SCL and SDA pins	—	—	—	—	—
D2	V _{IH}	High-level input voltage	0.7 V _{CC}	—	—	V	—
D3	V _{IL}	Low-level input voltage	—	—	0.3 V _{CC} 0.2 V _{CC}	V V	V _{CC} ≥ 2.5V V _{CC} < 2.5V
D4	V _{HYS}	Hysteresis of Schmitt Trigger inputs (SDA, SCL pins)	0.05 V _{CC}	—	—	V	V _{CC} ≥ 2.5V (Note 1)
D5	V _{OL}	Low-level output voltage	—	—	0.40	V	I _{OL} = 3.0 mA, V _{CC} = 4.5V I _{OL} = 2.1 mA, V _{CC} = 2.5V
D6	I _{LI}	Input leakage current	—	—	±1	μA	V _{IN} = V _{SS} or V _{CC} , WP = V _{SS} V _{IN} = V _{SS} or V _{CC} , WP = V _{CC}
D7	I _{LO}	Output leakage current	—	—	±1	μA	V _{OUT} = V _{SS} or V _{CC}
D8	C _{IN} , C _{OUT}	Pin capacitance (all inputs/outputs)	—	—	10	pF	V _{CC} = 5.0V (Note 1) TA = 25°C, F _{CLK} = 1 MHz
D9	I _{CC} write	Operating current	—	0.1	3	mA	V _{CC} = 5.5V, SCL = 400 kHz
D10	I _{CC} read		—	0.05	400	μA	
D11	I _{CCS}	Standby current	— —	0.01 —	1 5	μA μA	Industrial Automotive SDA = SCL = V _{CC} = 5.5V A0, A1, A2, WP = V _{SS}

Note 1: This parameter is periodically sampled and not 100% tested.

2: Typical measurements taken at room temperature.

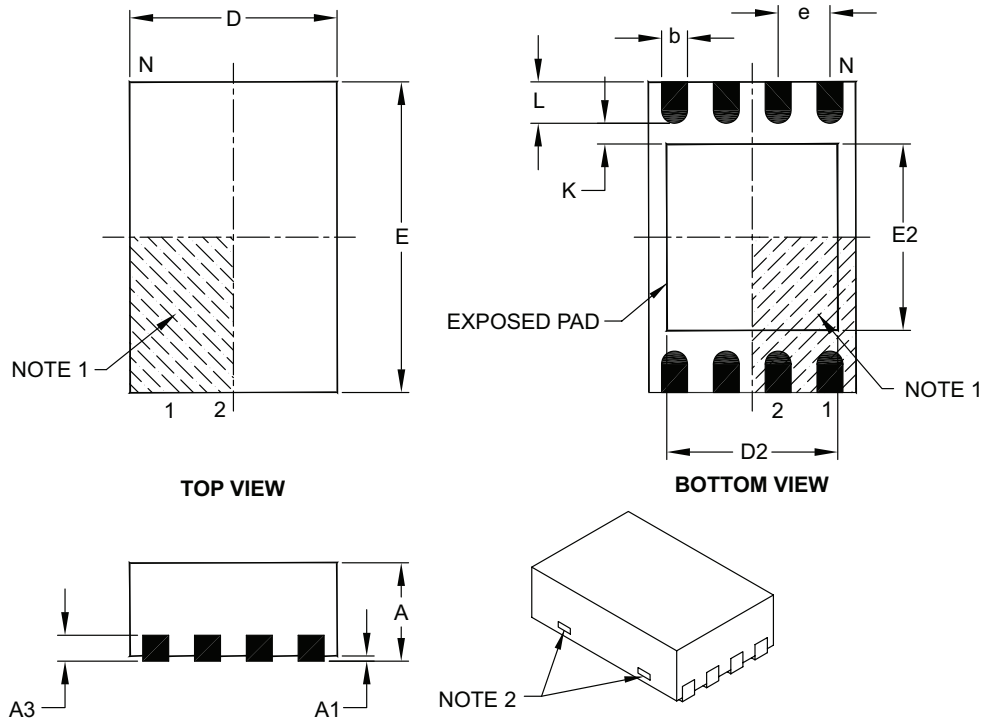
TABLE 1-2: AC CHARACTERISTICS

AC CHARACTERISTICS			Industrial (I): TA = -40°C to +85°C, VCC = +1.7V to +5.5V Automotive (E): TA = -40°C to +125°C, VCC = +2.5V to +5.5V			
Param. No.	Symbol	Characteristic	Min.	Max.	Units	Conditions
1	FCLK	Clock Frequency	— —	400 100	kHz	2.5V ≤ VCC ≤ 5.5V 1.7V ≤ VCC < 2.5V (24AA32A)
2	THIGH	Clock High Time	600 4000	— —	ns	2.5V ≤ VCC ≤ 5.5V 1.7V ≤ VCC < 2.5V (24AA32A)
3	TLOW	Clock Low Time	1300 4700	— —	ns	2.5V ≤ VCC ≤ 5.5V 1.7V ≤ VCC < 2.5V (24AA32A)
4	TR	SDA and SCL Rise Time (Note 1)	— —	300 1000	ns	2.5V ≤ VCC ≤ 5.5V 1.7V ≤ VCC < 2.5V (24AA32A)
5	TF	SDA and SCL Fall Time	—	300	ns	(Note 1)
6	THD:STA	Start Condition Hold Time	600 4000	— —	ns	2.5V ≤ VCC ≤ 5.5V 1.7V ≤ VCC < 2.5V (24AA32A)
7	TSU:STA	Start Condition Setup Time	600 4700	— —	ns	2.5V ≤ VCC ≤ 5.5V 1.7V ≤ VCC < 2.5V (24AA32A)
8	THD:DAT	Data Input Hold Time	0	—	ns	(Note 2)
9	TSU:DAT	Data Input Setup Time	100 250	— —	ns	2.5V ≤ VCC ≤ 5.5V 1.7V ≤ VCC < 2.5V (24AA32A)
10	TSU:STO	Stop Condition Setup Time	600 4000	— —	ns	2.5V ≤ VCC ≤ 5.5V 1.7V ≤ VCC < 2.5V (24AA32A)
11	TSU:WP	WP Setup Time	600 4000	— —	ns	2.5V ≤ VCC ≤ 5.5V 1.7V ≤ VCC < 2.5V (24AA32A)
12	THD:WP	WP Hold Time	1300 4700	— —	ns	2.5V ≤ VCC ≤ 5.5V 1.7V ≤ VCC < 2.5V (24AA32A)
13	TAA	Output Valid from Clock (Note 2)	— —	900 3500	ns	2.5V ≤ VCC ≤ 5.5V 1.7V ≤ VCC < 2.5V (24AA32A)
14	TBUF	Bus free time: Time the bus must be free before a new transmission can start	1300 4700	— —	ns	2.5V ≤ VCC ≤ 5.5V 1.7V ≤ VCC < 2.5V (24AA32A)
15	TOF	Output Fall Time from VIH Minimum to VIL Maximum	20+0.1CB —	250 250	ns	2.5V ≤ VCC ≤ 5.5V 1.7V ≤ VCC < 2.5V (24AA32A)
16	TSP	Input Filter Spike Suppression (SDA and SCL pins)	—	50	ns	(Notes 1 and 3)
17	TWC	Write Cycle Time (byte or page)	—	5	ms	—
18	—	Endurance	1M	—	cycles	25°C, (Note 4)

Note 1: Not 100% tested. CB = total capacitance of one bus line in pF.

- 2:** As a transmitter the device must provide an internal minimum delay time to bridge the undefined region (minimum 300 ns) of the falling edge of SCL to avoid unintended generation of Start or Stop conditions.
- 3:** The combined TSP and VHYS specifications are due to new Schmitt Trigger inputs which provide improved noise spike suppression. This eliminates the need for a TI specification for standard operation.
- 4:** This parameter is not tested but ensured by characterization. For endurance estimates in a specific application, please consult the Total Endurance™ Model which can be obtained on Microchip's web site at

8-Lead Plastic Dual Flat, No Lead Package (MC) – 2x3x0.9 mm Body [DFN]



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	0.50 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3	0.20 REF		
Overall Length	D	2.00 BSC		
Overall Width	E	3.00 BSC		
Exposed Pad Length	D2	1.30	–	1.75
Exposed Pad Width	E2	1.50	–	1.90
Contact Width	b	0.18	0.25	0.30
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package may have one or more exposed tie bars at ends.
- Package is saw singulated.
- Dimensioning and tolerancing per ASME Y14.5M.
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-123B

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>		<u>X</u>	<u>/XX</u>
Device	Temperature Range		Package
Device: <ul style="list-style-type: none"> 24AA32A: 1.7V, 32 Kbit I²C Serial EEPROM 24AA32AT: 1.7V, 32 Kbit I²C Serial EEPROM (Tape and Reel) 24LC32A: 2.5V, 32 Kbit I²C Serial EEPROM 24LC32AT: 2.5V, 32 Kbit I²C Serial EEPROM (Tape and Reel) 			
Temperature Range:		I = -40°C to +85°C	
		E = -40°C to +125°C	
Package:		P = Plastic DIP (300 mil body), 8-lead	
		SN = Plastic SOIC (3.90 mm body), 8-lead	
		SM = Plastic SOIC (5.28 mm body), 8-lead	
		ST = Plastic TSSOP (4.4 mm), 8-lead	
		MS = Plastic Micro Small Outline (MSOP), 8-lead	
		MC = 2x3 DFN, 8-lead	
		Examples: <ul style="list-style-type: none"> a) 24AA32A-I/P: Industrial Temperature, 1.7V, PDIP package b) 24AA32A-I/SN: Industrial Temperature, 1.7V, SOIC package c) 24AA32A-I/SM: Industrial Temperature, 1.7V, SOIC (5.28 mm) package d) 24AA32A-I/ST: Industrial Temperature, 1.7V, TSSOP package e) 24LC32A-I/P: Industrial Temperature, 2.5V, PDIP package f) 24LC32A-E/SN: Automotive Temperature, 2.5V SOIC package g) 24LC32A-E/SM: Automotive Temperature, 2.5V SOIC (5.28 mm) package h) 24LC32AT-I/ST: Industrial Temperature, 2.5V, TSSOP package, Tape and Reel 	